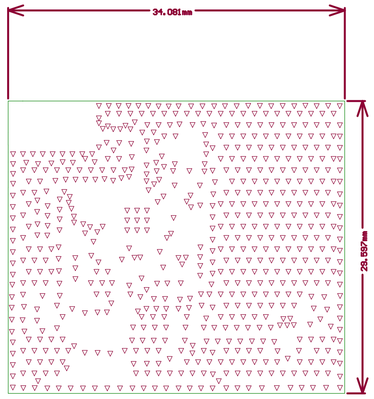
Fabrication Notes:

1. All dimensions in inches. Tolerance = +/- 0.005 unless noted otherwise.
2. All materials: laminates, resins, metallizations and soldermask to be compliant with RoHS and WEEE directives.
3. Use 370 HR FR-4 or similar grade glass epoxy.
4. Tg > 170 degrees C, glass transition temperature.
5. TD > 350 degrees C, thermal decomposition.
6. Minimum flammibility rating UL94V-0, maximum dissipation factor 0.025.
7. Adjust prepreg for 0.032 , +/- 0.003 finished thickness measured over soldermask.
8. Copper thickness 0.0014 , (1 oz).
9. Hole size tolerance = +/- 0.003 unless noted otherwise.
10. Hole centers and pad centers to be concentric within 0.002 .
11. Drill chart dimensions are finished hole sizes.
12. Finish - immersion gold over nickel. No exposed bare copper permitted.
13. Solder mask over bare copper, LPI clas 2 gen. industrial registration +/- 0.004.
14. No coverage on solder pads permitted.
15. Refer to soldermask gerbers for tenting of vias.
16. White silkscreen legend over red soldermask - both sides.
17. Manufacturer icons not permitted on the silkscreen top layer.
18. PCB serialization/panel placement ID on silkscreen bottom.
19. Full electrical test against IPC-356A netlist.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	28.00mil	4.48	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				
Total board thickness:			31.60mil		

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Pad Shape
▽	643	0.250mm	PTH	Round	Top Layer - Bottom Layer	Rounded
	643 Total					



IoT Wireless Hardware Applications

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617-951-0200

TITLE: EFR32xG22 Low Cost Reference Design

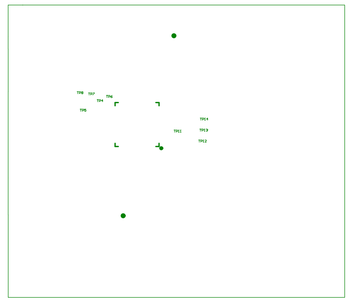
FILE NAME: EFR32xG22_LC_REF_DES_RevA01.PcbDoc

Board NO.: EFR32xG22_LCRD

REV: A01

Layer: Drill Drawing

DATE: 9/25/2020



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FILE NAME:
EFR32xG22_LC_REF_DES_RevA01.PcbDoc

Board NO.:
EFR32xG22_LCRD

REV:
A01

Layer:
Top Overlay

DATE:
9/25/2020

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EFR32xG22_LC_REF_DES_RevA01.PcbDoc

Board NO.:
EFR32xG22_LCRD

REV:
A01

Layer:
Top Paste

DATE:
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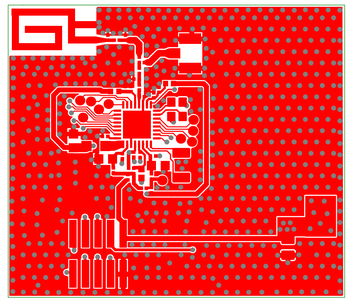
EFR32xG22_LC_REF_DES_RevA01.PcbDoc

Board NO.:	REV:
EFR32xG22_LCRD	A01
Layer: Top Solder	DATE: 9/25/2020



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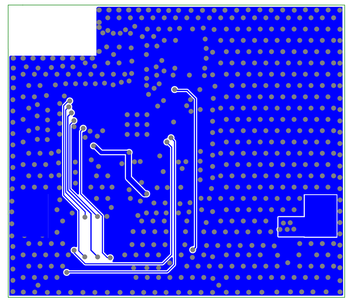
Board NO.:	REV:
EFR32xG22_LCRD	A01
Layer: Top Layer	DATE: 9/25/2020



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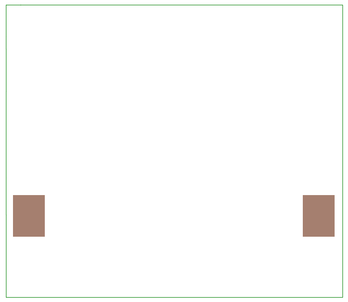
Board NO.:	REV:
EFR32xG22_LCRD	A01

Layer:	DATE:
Bottom Layer	9/25/2020



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REV:
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Layer:
Bottom Solder

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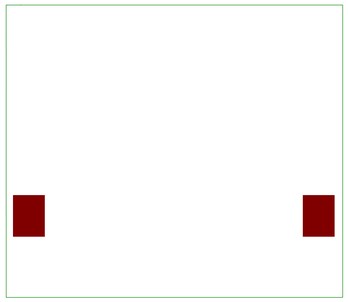
9/25/2020



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Board NO.:
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REV:
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Layer:
Bottom Paste

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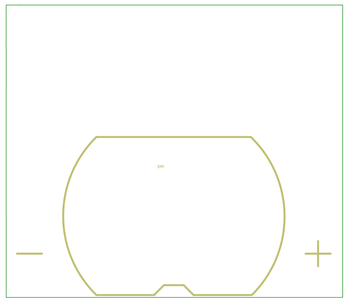

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